

SOT952-1

plastic ball grid array package; 432 balls; body 35 x 35 x 1.75 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA432
Package type industry code	BGA432
Package style descriptive code	BGA (ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	21-6-2006

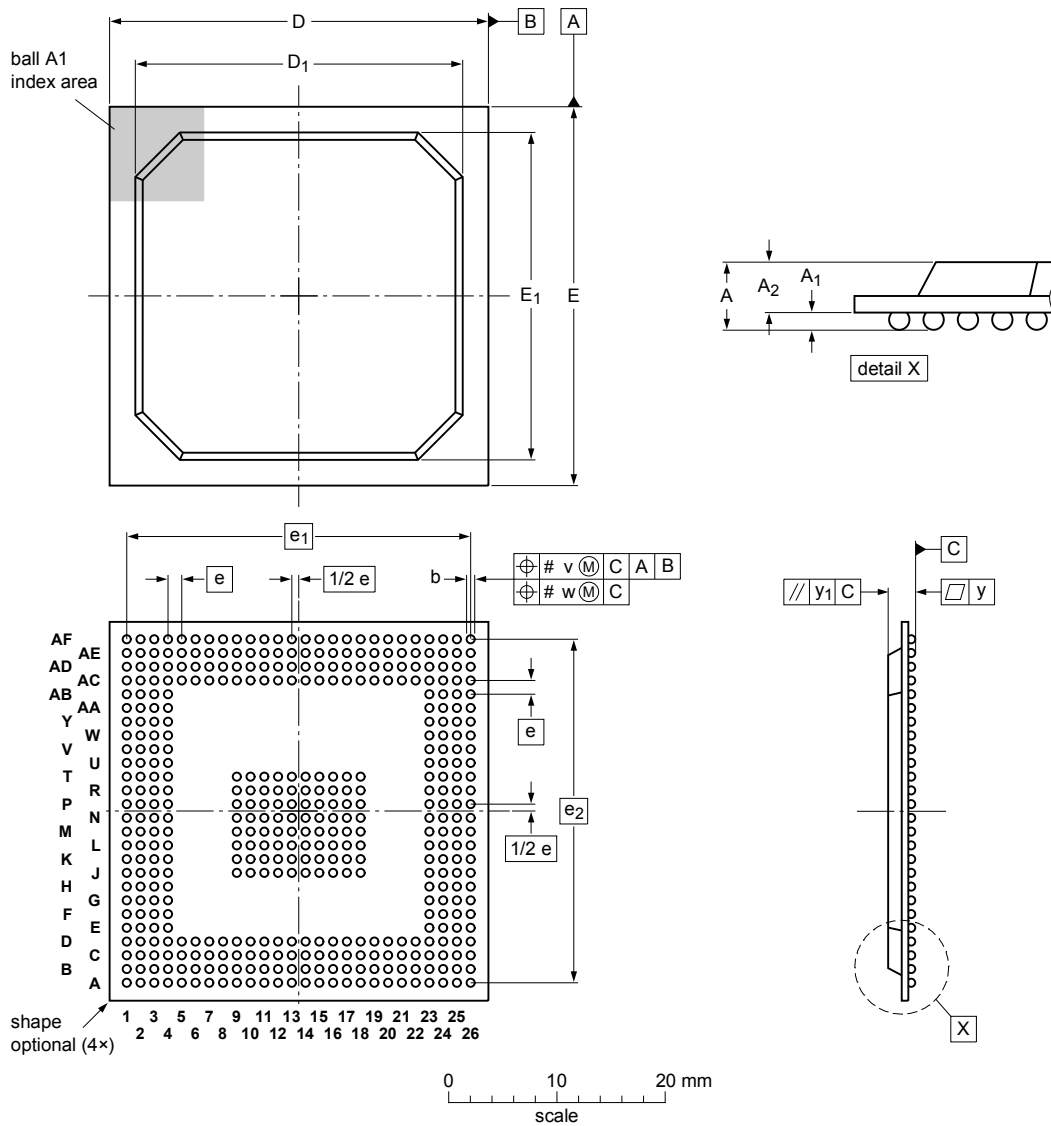
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	34.8	-	35	35.2	mm
E	package width	34.8	-	35	35.2	mm
A	seated height	[tbd]	-	2.55	2.55	mm
A ₂	package height	1.6	-	1.75	1.85	mm
n ₂	actual quantity of termination	-	-	432	-	



2. Package outline

BGA432: plastic ball grid array package; 432 balls; body 35 x 35 x 1.75 mm SOT952-1



DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	A ₁	A ₂	b	D	D ₁	E	E ₁	e	e ₁	e ₂	v	w	y	y ₁
mm	2.55	0.7 0.5	1.85 1.60	0.9 0.6	35.2 34.8	30.75 29.75	35.2 34.8	30.75 29.75	1.27	31.75	31.75	0.3	0.15	0.2	0.35

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT952-1	144E	MS-034	---			06-06-16 06-06-21

Fig. 1. Package outline BGA432 (SOT952-1)

3. Legal information

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